

LINEAR TECHNOLOGY MATERIALS DECLARATION

LT6660KCDC-3.3#TRMPBF		(Engineering Calculation)		DFN 2mm X 2mm Exp. Pad				
(printed on: 7/26/2011 6:30:20 AM)				TOTAL MASS (g):		0.009136325		
COMPONENT	VENDOR/	CONSTITUENT	CAS	CONSTITUENT	CONSTITUENT	CONSTITUENT		
MATERIAL	INDUSTRY NAMES	NAME	NUMBER	MASS (g)	(PPM) OF MATERIAL	(PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000321	1000000	35134.48		
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.002935	975000	321245.1		
		Iron (Fe)	7439-89-6	7.20E-05	24000	7880.631		
		Phosphorus (P)	7723-14-0	1.00E-06	300	109.4532		
		Zinc (Zn)	7440-66-6	2.00E-06	700	218.9064		
		Nickel (Ni)	7440-02-0	0	0	0		
		Silicon (Si)	7440-21-3	0	0	0		
		Magnesium (Mg)	7439-95-4	0	0	0		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead Frame Total:				0.00301	1000000	329454.2
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0		
		Exter. Plating Sn	7440-31-5	0.000136325	1000000	14921.19		
		External Plating Total:				0.000136325	1000000	14921.19
		Inter. Plating Ni	7440-02-0	0	0	0		
		Inter. Plating Ag	7440-22-4	7.20E-05	1000000	7880.631		
		Internal Plating Total:				7.20E-05	1000000	7880.631
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000281	750000	30756.35		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead (Pb)	7439-92-1	0	0	0		
		Silica (SiO2)	60676-86-0	0	0	0		
		Metal Oxide		0	0	0		
		Antimony (Sb)	7440-36-0	0	0	0		
		Resin (EP)		9.40E-05	250000	10288.6		
Die Attach Total:				0.000375	1000000	41044.95		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000677	130000	74099.81		
		Bromine (Br)	40039-93-8	0	0	0		
		Silica (SiO2)	60676-86-0	0.004481	860000	490459.8		
		Antimony	1309-64-4	0	0	0		
		Trioxide (Sb2O3)						
		Metal Hydroxid		0	0	0		
		Carbon Black (C)	1333-86-4	5.20E-05	10000	5691.566		
Encapsulation Total:				0.00521	1000000	570251.2		
Bond Wire	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	1.20E-05	1000000	1313.438		
Estimated								
				TOTAL MASS (g):		0.009136325		